

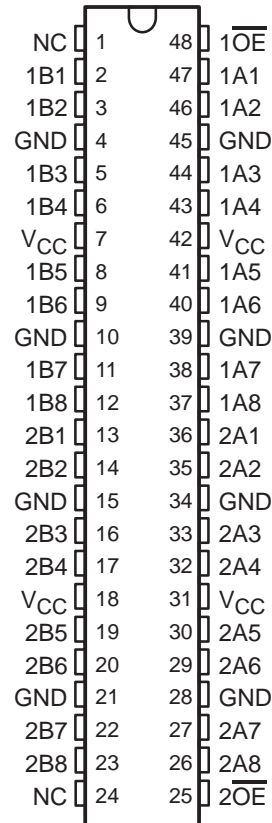
- Member of Texas Instruments' Widebus™ Family
- Standard '16245-Type Pinout
- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

description

The SN74CBT16245 device provides 16 bits of high-speed TTL-compatible bus switching in a standard '16245 device pinout. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The device is organized as two 8-bit low-impedance switches with separate output-enable (\overline{OE}) inputs. When \overline{OE} is low, the switch is on, and data can flow from the A port to the B port, or vice versa. When \overline{OE} is high, the switch is open, and the high-impedance state exists between the two ports.

DGG, DGV, OR DL PACKAGE (TOP VIEW)



NC – No internal connection

ORDERING INFORMATION

TA	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	SSOP – DL	Tube	SN74CBT16245DL	CBT16245
		Tape and reel	SN74CBT16245DLR	
	TSSOP – DGG	Tape and reel	SN74CBT16245DGGR	CBT16245
	TVSOP – DGV	Tape and reel	SN74CBT16245DGVR	CY245

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE (each 8-bit bus switch)

INPUT \overline{OE}	FUNCTION
L	A port = B port
H	Disconnect



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP†	MAX	UNIT	
V_{IK}		$V_{CC} = 4.5\text{ V}$,	$I_I = -18\text{ mA}$			-1.2	V	
I_I		$V_{CC} = 0$,	$V_I = 5.5\text{ V}$			10	μA	
		$V_{CC} = 5.5\text{ V}$,	$V_I = 5.5\text{ V or GND}$			± 1		
I_{CC}		$V_{CC} = 5.5\text{ V}$,	$I_O = 0$,			3	μA	
ΔI_{CC}^\ddagger	Control inputs	$V_{CC} = 5.5\text{ V}$,	One input at 3.4 V,	Other inputs at V_{CC} or GND		2.5	mA	
C_i	Control inputs	$V_I = 3\text{ V or 0}$				3.5	pF	
$C_{iO}(\text{OFF})$		$V_O = 3\text{ V or 0}$,	$\overline{OE} = V_{CC}$			4.5	pF	
r_{on}^\S		$V_{CC} = 4\text{ V}$, TYP at $V_{CC} = 4\text{ V}$	$V_I = 2.4\text{ V}$,	$I_I = 15\text{ mA}$		14	20	Ω
			$V_{CC} = 4.5\text{ V}$	$V_I = 0$	$I_I = 64\text{ mA}$		5	
		$I_I = 30\text{ mA}$				5	7	
		$V_I = 2.4\text{ V}$,		$I_I = 15\text{ mA}$		8	12	

† All typical values are at $V_{CC} = 5\text{ V}$ (unless otherwise noted), $T_A = 25^\circ\text{C}$.

‡ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

§ Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

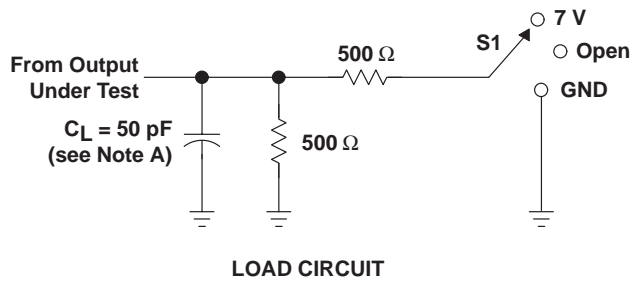
PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4\text{ V}$		$V_{CC} = 5\text{ V} \pm 0.5\text{ V}$		UNIT
			MIN	MAX	MIN	MAX	
t_{pd}^{\parallel}	A or B	B or A	0.35		0.25		ns
t_{en}	\overline{OE}	A or B		6.1	1.2	5.6	ns
t_{dis}	\overline{OE}	A or B		7.5	3.9	7.7	ns

\parallel The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

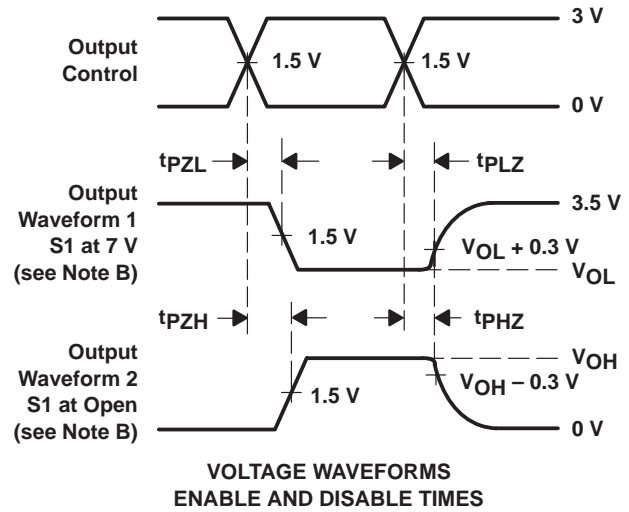
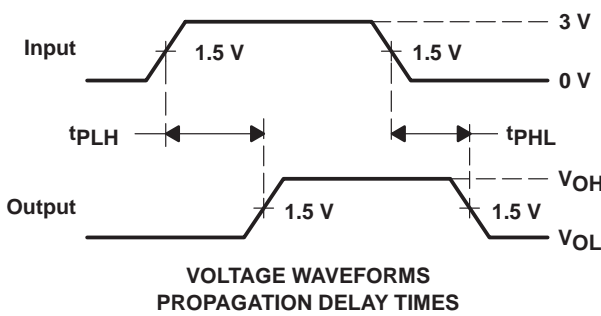
SN74CBT16245 16-BIT FET BUS SWITCH

SCDS070C – JULY 1998 – REVISED OCTOBER 2000

PARAMETER MEASUREMENT INFORMATION



TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 - The outputs are measured one at a time with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - t_{PZL} and t_{PZH} are the same as t_{en} .
 - t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74CBT16245DGGR	LIFEBUY	TSSOP	DGG	48	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CBT16245	
SN74CBT16245DGVR	LIFEBUY	TVSOP	DGV	48	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CY245	
SN74CBT16245DL	LIFEBUY	SSOP	DL	48	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CBT16245	
SN74CBT16245DLR	LIFEBUY	SSOP	DL	48	1000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CBT16245	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74CBT16245DGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1
SN74CBT16245DGVR	TVSOP	DGV	48	2000	330.0	16.4	7.1	10.2	1.6	12.0	16.0	Q1
SN74CBT16245DLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74CBT16245DGGR	TSSOP	DGG	48	2000	367.0	367.0	45.0
SN74CBT16245DGVR	TVSOP	DGV	48	2000	356.0	356.0	35.0
SN74CBT16245DLR	SSOP	DL	48	1000	367.0	367.0	55.0

TUBE


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
SN74CBT16245DL	DL	SSOP	48	25	473.7	14.24	5110	7.87

DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN



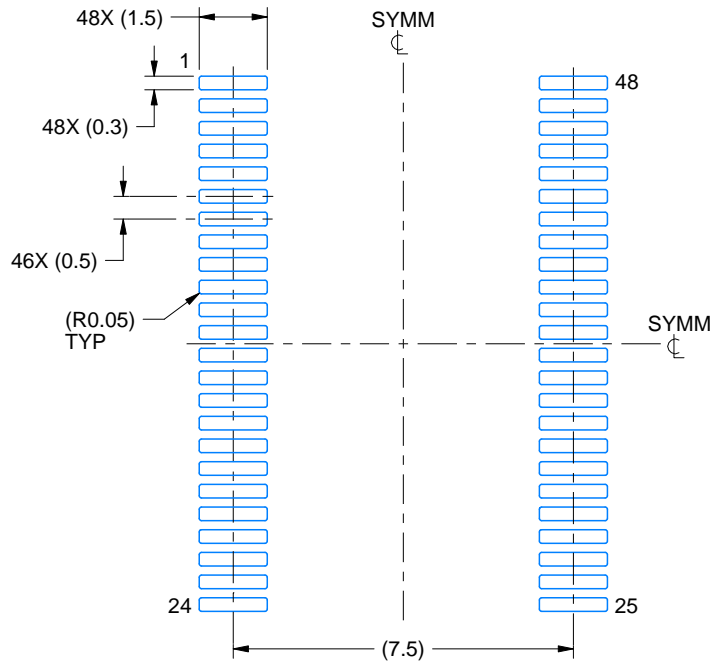
- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194

EXAMPLE BOARD LAYOUT

DGG0048A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
SCALE:6X



SOLDER MASK DETAILS

4214859/B 11/2020

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DGG0048A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4214859/B 11/2020

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN

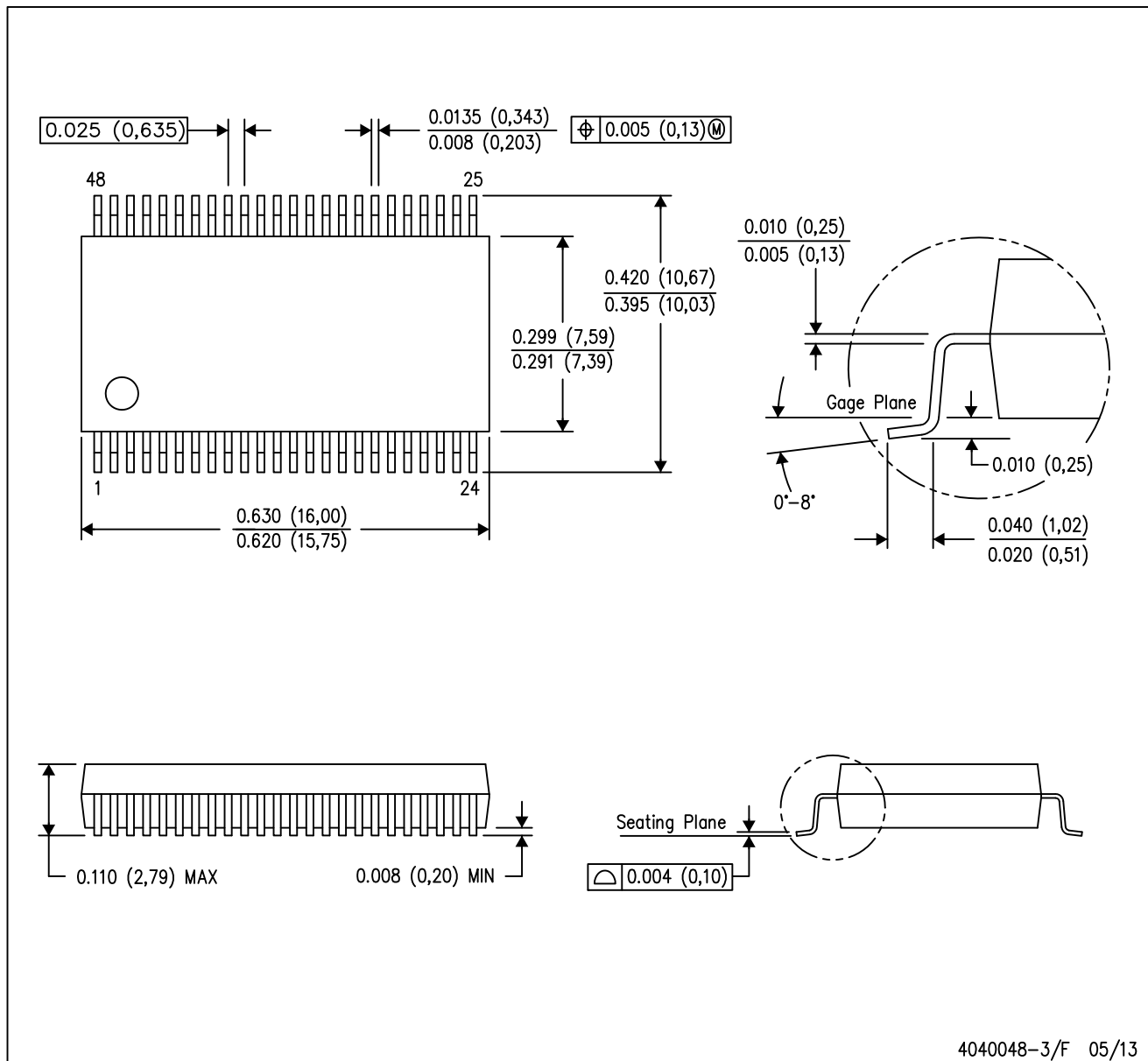


- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

MECHANICAL DATA

DL (R-PDSO-G48)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - Falls within JEDEC MO-118

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